

IGBT

SGH5N120RUF

Short Circuit Rated IGBT

General Description

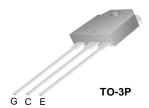
Fairchild's RUF series of Insulated Gate Bipolar Transistors (IGBTs) provides low conduction and switching losses as well as short circuit ruggedness. The RUF series is designed for applications such as motor control, uninterrupted power supplies (UPS) and general inverters where short circuit ruggedness is a required feature.

Features

- Short circuit rated 10 μ s @ $T_C = 100$ °C, $V_{GE} = 15V$
- · High speed switching
- Low saturation voltage: V_{CE(sat)} = 2.3 V @ I_C = 5A
- · High input impedance

Applications

AC & DC motor controls, general purpose inverters, robotics, and servo controls.





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Description		SGH5N120RUF	Units
V _{CES}	Collector-Emitter Voltage		1200	V
V _{GES}	Gate-Emitter Voltage		± 25	V
I _C	Collector Current	@ T _C = 25°C	8	А
	Collector Current	@ T _C = 100°C	5	А
I _{CM (1)}	Pulsed Collector Current		15	А
	Short Circuit Withstand Time	@ T _C = 100°C	10	μs
T _{SC}	Maximum Power Dissipation	@ T _C = 25°C	74	W
	Maximum Power Dissipation	@ T _C = 100°C	30	W
TJ	Operating Junction Temperature		-55 to +150	°C
T _{stg}	Storage Temperature Range		-55 to +150	°C
T _L	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds		300	°C

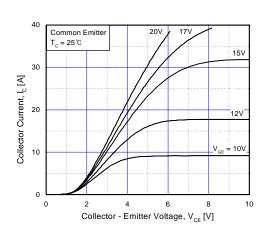
Notes

(1) Repetitive rating : Pulse width limited by max. junction temperature

Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		1.68	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		40	°C/W

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Char	racteristics					
BV _{CES}	Collector-Emitter Breakdown Voltage	$V_{GE} = 0V, I_C = 1mA$	1200			V
ΔB _{VCES} /	Temperature Coefficient of Breakdown	$V_{GE} = 0V, I_{C} = 1mA$		0.6		V/°C
ΔT_J	Voltage			0.0		۷, ٥
I _{CES}	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0V$			1	mA
I _{GES}	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$			± 100	nA
On Char	acteristics					
V _{GE(th)}	G-E Threshold Voltage	$I_C = 5mA$, $V_{CE} = V_{GE}$	3.5	5.5	7.5	V
	Collector to Emitter	$I_C = 5A$, $V_{GE} = 15V$		2.3	3.0	V
$V_{CE(sat)}$	Saturation Voltage	$I_C = 8A$, $V_{GE} = 15V$		2.8		V
Dynamic	c Characteristics					
C _{ies}	Input Capacitance	V 20V/V 0V		520		pF
C _{oes}	Output Capacitance	$V_{CE} = 30V_{,} V_{GE} = 0V_{,}$ f = 1MHz		45		pF
C _{res}	Reverse Transfer Capacitance	- I = IIVIH2		16		pF
t _{d(on)}	ng Characteristics Turn-On Delay Time			20		ns
t _r	Rise Time			60		ns
t _{d(off)}	Turn-Off Delay Time	$V_{CC} = 600 \text{ V}, I_{C} = 5\text{A},$		50	90	ns
t _f	Fall Time	$R_G = 30\Omega$, $V_{GE} = 15V$,		150	300	ns
E _{on}	Turn-On Switching Loss	Inductive Load, T _C = 25°C		0.35		mJ
E _{off}	Turn-Off Switching Loss			0.33		mJ
E _{ts}	Total Switching Loss			0.68	0.95	mJ
t _{d(on)}	Turn-On Delay Time			20		ns
t _r	Rise Time			70		ns
t _{d(off)}	Turn-Off Delay Time	$V_{CC} = 600 \text{ V}, I_{C} = 5\text{A},$		70	130	ns
t _f	Fall Time	$R_G = 30\Omega, V_{GE} = 15V,$		200	400	ns
E _{on}	Turn-On Switching Loss	Inductive Load, T _C = 125°C		0.38		mJ
E _{off}	Turn-Off Switching Loss	1		0.50		mJ
E _{ts}	Total Switching Loss			0.88	1.28	mJ
T _{sc}	Short Circuit Withstand Time	V _{CC} = 600 V, V _{GE} = 15V @ T _C = 100°C	10			μs
Q _q	Total Gate Charge			28	42	nC
	1	$V_{CE} = 600 \text{ V}, I_{C} = 5\text{A},$		2	-	0
Q _{ae}	Gate-Emitter Charge			3	5	nC
Q _{ge} Q _{gc}	Gate-Emitter Charge Gate-Collector Charge	V _{GE} = 15V		13	18	nC nC



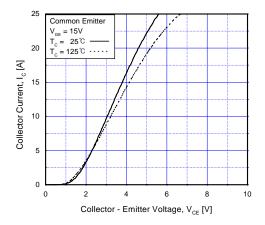
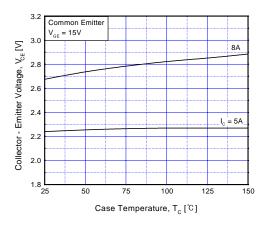


Fig 1. Typical Output Characteristics

Fig 2. Typical Saturation Voltage Characteristics



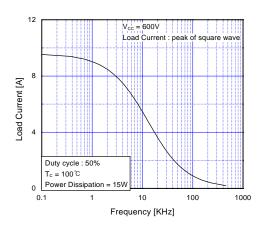
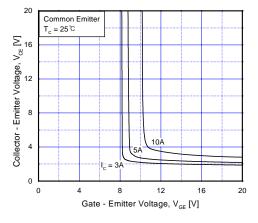


Fig 3. Saturation Voltage vs. Case Temperature at Variant Current Level

Fig 4. Load Current vs. Frequency



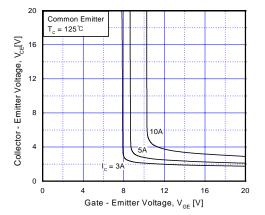
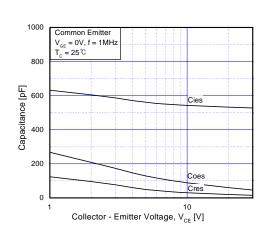


Fig 5. Saturation Voltage vs. V_{GE}

Fig 6. Saturation Voltage vs. V_{GE}

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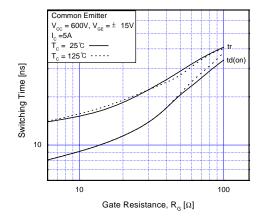
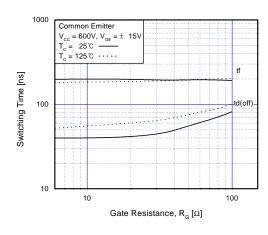


Fig 7. Capacitance Characteristics

Fig 8. Turn-On Characteristics vs.
Gate Resistance



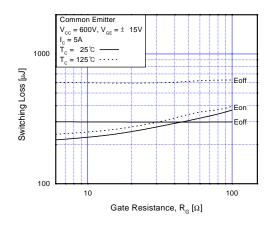
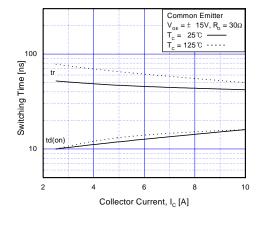


Fig 9. Turn-Off Characteristics vs.
Gate Resistance

Fig 10. Switching Loss vs. Gate Resistance



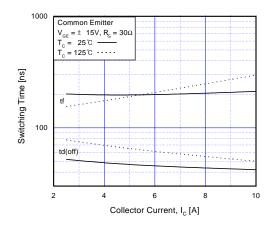
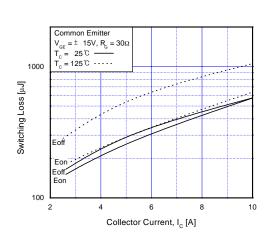


Fig 11. Turn-On Characteristics vs. Collector Current

Fig 12. Turn-Off Characteristics vs. Collector Current



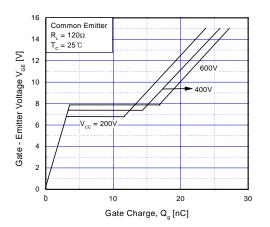
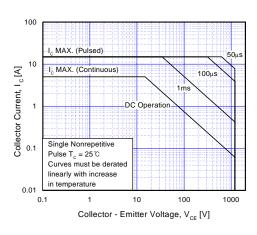


Fig 13. Switching Loss vs. Collector Current

Fig 14. Gate Charge Characteristics



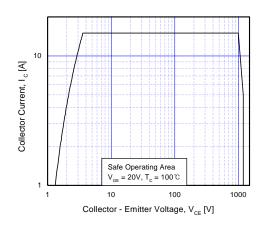


Fig 15. SOA Characteristics

Fig 16. Turn-Off SOA

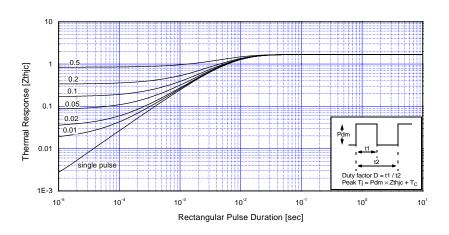
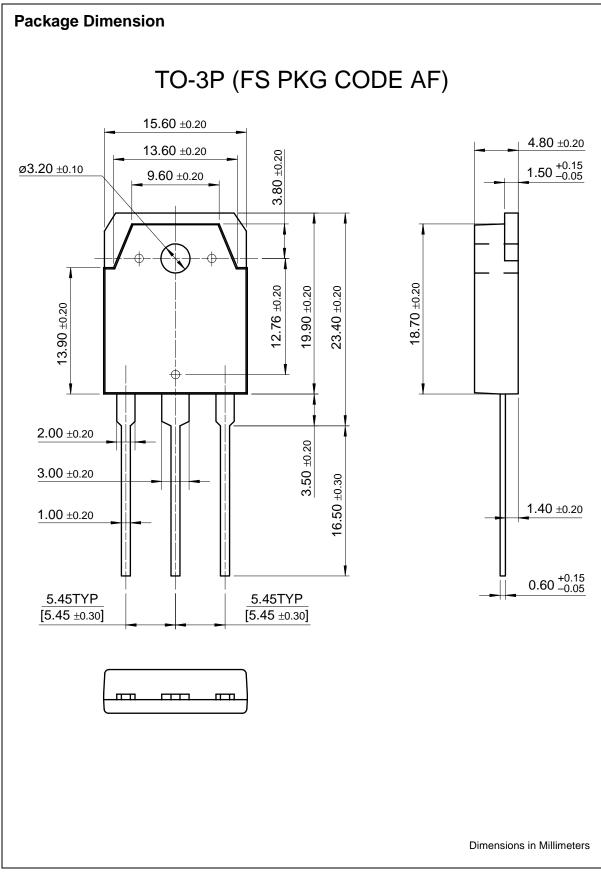


Fig 17. Transient Thermal Impedance of IGBT

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